

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



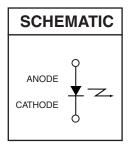




QEC112 QEC113

PACKAGE DIMENSIONS 0.116 (2.95) REFERENCE SURFACE 0.193 (4.90) 0.052 (1.32) 0.032 (0.082) $0.030^{\text{T}}(0.76)$ NOM 0.800 (20.3) MÌN 0.050 (1.27) CATHODE 0.100 (2.54) NOM 0.155 (3.94) 0.018 (0.46) SQ. (2X) NOTES: 1. Dimensions for all drawings are in inches (mm). 2. Tolerance of ± .010 (.25) on all non-nominal dimensions unless otherwise specified.





DESCRIPTION

The QEC11X is an 940 nm GaAs LED encapsulated in a clear peach tinted, plastic T-1 package.

FEATURES

- λ= 940 nm
- Chip material = GaAs
- Package type: T-1 (3mm)
- Matched Photosensor: QSC112
- Narrow Emission Angle, 24°
- High Output Power
- Package material and color: Clear, peach tinted plastic



QEC112 QEC113

ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise specified)							
Parameter	Symbol	Rating	Unit				
Operating Temperature	T _{OPR}	-40 to +100	°C				
Storage Temperature	T _{STG}	-40 to +100	°C				
Soldering Temperature (Iron)(2,3,4)	T _{SOL-I}	240 for 5 sec	°C				
Soldering Temperature (Flow)(2,3)	T _{SOL-F}	260 for 10 sec	°C				
Continuous Forward Current	I _F	50	mA				
Reverse Voltage	V _R	5	V				
Power Dissipation ⁽¹⁾	P _D	100	mW				

- 1. Derate power dissipation linearly 1.33 mW/°C above 25°C.
- 2. RMA flux is recommended.
- 3. Methanol or isopropyl alcohols are recommended as cleaning agents.
- 4. Soldering iron 1/16" (1.6mm) minimum from housing.

ELECTRICAL / OPTICAL CHARACTERISTICS (TA =25°C)								
PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS		
Peak Emission Wavelength	$I_F = 100 \text{ mA}$	λ_{PE}	_	940	_	nm		
Emission Angle	I _F = 100 mA	201/2		24		Deg.		
Forward Voltage	$I_F = 100 \text{ mA}, \text{ tp} = 20 \text{ ms}$	V _F	_	_	1.5	V		
Reverse Current	V _R = 5 V	I _R	_	_	10	μΑ		
Radiant Intensity QEC112	$I_F = 100 \text{ mA}, \text{ tp} = 20 \text{ ms}$	Ι _Ε	6	_	30	mW/sr		
Radiant Intensity QEC113	$I_F = 100 \text{ mA}, \text{ tp} = 20 \text{ ms}$	Ι _Ε	14	_	_	mW/sr		
Rise Time	1 100 mA	t _r	_	1000	_	ns		
Fall Time	I _F = 100 mA	t _f	_	1000	_	ns		



QEC112

QEC113

TYPICAL PERFORMANCE CURVES

Fig.1 Normalized Radiant Intensity vs. Forward Current

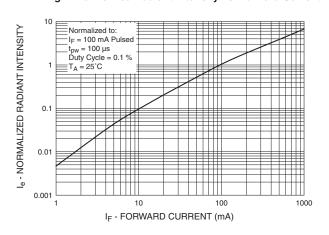


Fig.2 Coupling Characteristics of QEC11X And QSC11X

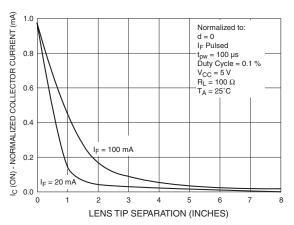


Fig.3 Forward Voltage vs. Ambient Temperature

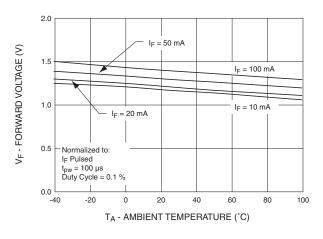


Fig. 4 Normalized Intensity vs. Wavelength

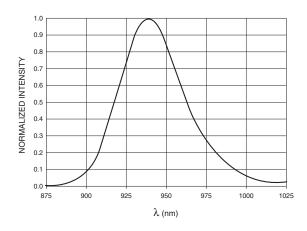
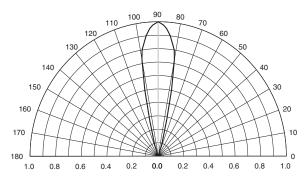


Fig. 5 Radiation Diagram





QEC112

QEC113

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body,or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.